

This listing of claims will replace all prior versions and listings of claim in the application:

**Listing of the Claims:**

Claims 1-23 (cancelled).

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Cy 24. (new) A method of fabricating a semiconductor wafer comprising the steps of:  
loading a wafer into a wafer process station using a transport system;  
processing the wafer in the process station;  
transferring the wafer to a metrology station spaced apart but coupled to the  
process station using the transport system;  
generating a broadband light beam;  
obtaining a first measurement of the spectral content of the broadband light beam  
which has been reflected from the wafer;  
obtaining a second measurement of the spectral content of the broadband light  
beam which has not been reflected from the wafer; and  
evaluating the sample <sup>beam</sup> based on the first and second measurements, where the  
second measurement is used to correct for system characteristics.

25. (new) The method as recited in claim 24, wherein said first and second  
measurements are obtained simultaneously.

26. (new) The method as recited in claim 24, wherein the broadband light beam is  
generated by a UV light source.

27. (new) The method as recited in claim 24, wherein the broadband light beam is  
generated by a light source defined by at least one lamp, said light source emitting a range of  
wavelengths, said range of wavelengths including visible and ultraviolet light.

28. (new) The method as recited in claim 24, wherein the step of processing the  
wafer includes polishing.

29. (new) The method as recited in claim 24, wherein the broadband light beam is generated by a lamp selected from the group consisting of a UV xenon lamp, a tungsten lamp, a deuterium lamp and a xenon lamp.

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